

REMARKS

In this Amendment, Applicant has amended Claims 1, 4 and 8 to specify various embodiments of the present invention and overcome the rejection. In addition, the specification has been amended to correct a clerical error. The amendment is editorial in nature. It is respectfully submitted that no new matter has been introduced by the amended claims and specification. All claims are now present for examination and favorable reconsideration is respectfully requested in view of the preceding amendments and the following comments.

OBJECTION TO SPECIFICATION:

The specification has been objected as containing informality.

It is respectfully submitted that the informality contained in the specification has been corrected by changing "Ns" to "Na" at page 15, line 19. Therefore, objection to the specification is overcome and withdrawal of the objection is respectfully requested.

REJECTIONS UNDER 35 U.S.C. § 102:

Claims 1 – 7 have been rejected under 35 U.S.C. § 102 (b) as allegedly being anticipated by Kusano et al. (US 6,190,014), hereinafter Kusano. Claims 1 – 7 have been rejected under 35 U.S.C. § 102 (e) as allegedly being anticipated by Aastuen et al. (US 6,786,604), hereinafter Aastuen.

Applicant traverses the rejection and respectfully submits that the present-claimed invention is not anticipated by the cited reference. More specifically, Claims 1 and 4 have been amended to indicate that "an average thickness of the bonding layer being in the range from 2 μ m to 10 μ m, a difference in thickness of the bonding layer between a thickest portion and a thinnest portion thereof being 12 μ m or smaller." Claims 2, 3, and

5 – 7 also include these features due to their dependency on Claims 1 and 4. The support can be found on page 14, lines 3 to 10 and page 15, lines 6 to 10 of the specification.

The embodiment of the present invention as defined in amended Claims 1 and 4 provides features that give high resolution to a projected image, which could otherwise be lowered due to wavefront aberration that occurs on the bonding layer, as discussed on page 2, line 32 to page 3, line 2 of the specification.

Kusano teaches 22 μm or lower (preferably 15 μm) in difference in thickness of the adhesive layer (col. 10, lines 26 – 29), which could correspond to the claimed difference in thickness of the bonding layer. However, it does not teach or discuss the average thickness of the adhesive layer.

Aastuen discloses 225 μm for the adhesive layer (col. 20, line 5) much larger than the claimed average thickness of the adhesive layer. However, it does not teach or disclose the difference in the thickness of the adhesive layer.

Therefore, the newly presented claim is not anticipated by Kusano or Aastuen and the rejection under 35 U.S.C. § 102 (b) has been overcome. Accordingly, withdrawal of the rejection under 35 U.S.C. § 102 (b) is respectfully requested.

REJECTIONS UNDER 35 U.S.C. §103:

Claims 8 – 15 have been rejected under 35 U.S.C. §103 as allegedly being unpatentable over by Suzuki et al. (US Patent Publication No. 2002/0097382) in view of Aastuen.

Applicant traverses the rejection and respectfully submits that the embodiments of present-claimed invention are not obvious over the cited prior art references. More specifically, Claim 8 has been amended to indicate that “an average thickness of the bonding layer being in the range from 2 μm to 10 μm , a difference in thickness of the bonding layer between a thickest portion and a thinnest portion thereof being 12 μm or

smaller.” Claims 9 – 15 also include these features due to their dependency on Claim 8. It is respectfully submitted that there are significant differences between the embodiments of the present invention and the disclosures in Aastuen as indicated above.

In addition, as admitted by the Examiner, Suzuki does not disclose the thickness of the bonding layer. Therefore, there is no motivation or reasonable expectation of success to combine Aastuen with Suzuki. Even if they are combined, they fail to disclose or teach the present invention as claimed.

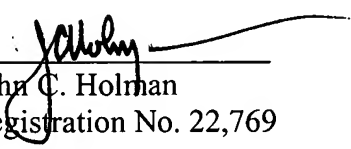
Therefore, the rejection under 35 U.S.C. §103, second paragraph, has been overcome. Accordingly, withdrawal of the rejections under 35 U.S.C. §103 is respectfully requested.

Having overcome all outstanding grounds of rejection, the application is now in condition for allowance, and prompt action toward that end is respectfully solicited.

Respectfully submitted,

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